

# Multi-sensor chip for the investigation of different types of metal oxides for the detection of $\text{H}_2\text{O}_2$ in the ppm range

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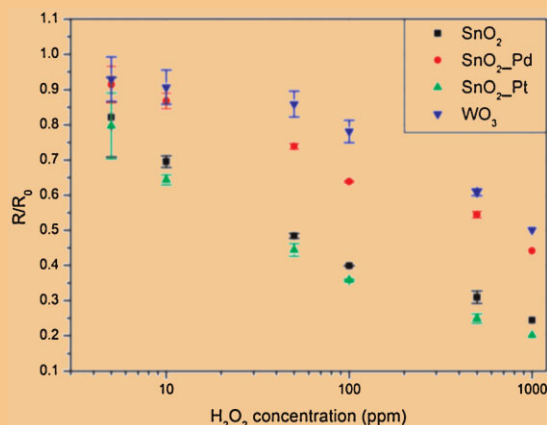
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**Keywords** doped metal oxide, gas sensor, hydrogen peroxide, multi-sensor, tin oxide, tungsten oxide

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In this work, a multi-sensor chip for the investigation of the sensing properties of different types of metal oxides towards hydrogen peroxide in the ppm range is presented. The fabrication process and physical characterization of the multi-sensor chip are described. Pure  $\text{SnO}_2$  and  $\text{WO}_3$  as well as Pd- and Pt-doped  $\text{SnO}_2$  films are characterized in terms of their sensitivity to  $\text{H}_2\text{O}_2$ . The sensing films have been prepared by drop-coating of water-dispersed nano-powders. A physical characterization, including scanning electron microscopy and X-ray diffraction analysis of the deposited metal-oxide films, was done. From the measurements in hydrogen peroxide atmosphere, it could be shown, that all of the tested metal oxide films are suitable for the detection of  $\text{H}_2\text{O}_2$  in the ppm range. The highest sensitivity and reproducibility was achieved using Pt-doped  $\text{SnO}_2$ .



Calibration plot of a  $\text{SnO}_2$ ,  $\text{WO}_3$ , Pt-, and Pd-doped  $\text{SnO}_2$  gas sensor for  $\text{H}_2\text{O}_2$  concentrations in the ppm range.

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**1 Introduction** Hydrogen peroxide ( $\text{H}_2\text{O}_2$ ) is a commonly used sterilizing agent for carton packages in aseptic food filling processes. Due to its ability to decompose to water and oxygen it is advantageous compared to other chemical sterilization agents in terms of environmental compatibility [1]. However, in view of its strong oxidizing properties, special precautions with regard to the workplace security in the surrounding of sterilization plants employing  $\text{H}_2\text{O}_2$  as sterilizing agent have to be taken into account, especially when applied in vapor phase. Therefore, the American Conference of Governmental Industrial Hygienists (ACGIH) has assigned hydrogen peroxide a threshold limit

value (TLV) of 1 ppm. For monitoring the concentration in danger zones and in the workplace environment, electrochemical sensor systems from the German company *Dräger* have been established. These monitoring systems typically cover a measuring range either in the lower (0–20 ppm) or in the upper (1000–7000 ppm) range, but nothing in between or beyond that, nor are these operable in high flow conditions. With regard to the aseptic filling processes, there is a high demand for monitoring the  $\text{H}_2\text{O}_2$  concentration in the exhaust air of such sterilization plants, which typically is in the ppm concentration range, not only with respect to the TLV but also in terms of process monitoring.

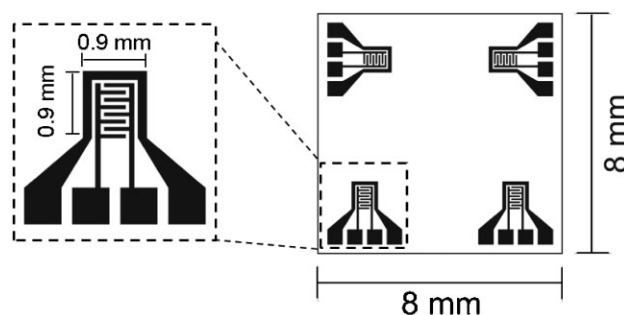
Previous works have shown that calorimetric-type gas sensors are suitable for monitoring  $\text{H}_2\text{O}_2$  concentrations in the range between 1 and 8% v/v [2–6]. This is equally true for commercially available metal-oxide-semiconductor gas sensors [7]. While the lower limit of detection (LOD) in case of the calorimetric gas sensors, which determine the exothermic energy due to a catalytic reaction, is in the range of approximately 5000 ppm, it is assumed that metal-oxide gas sensors respond at lower concentrations. Within the frame of this work, different types of metal oxides shall be investigated on their response to  $\text{H}_2\text{O}_2$  in the range between 5 and 1000 ppm. Therefore, a multi-sensor chip, including four individually controllable sensor structures, based on a sapphire substrate with the size of  $8 \times 8 \text{ mm}^2$  has been developed. The four sensor structures have been prepared with different types of metal oxides. On one hand, two of the structures were prepared with pure tin oxide ( $\text{SnO}_2$ ) and tungsten oxide ( $\text{WO}_3$ ) films. On the other hand, two sensor structures have been prepared with palladium- (Pd) and platinum black- (Pt) doped  $\text{SnO}_2$ , respectively. The doping of metal oxides with catalytically active species is a common strategy to enhance catalytical effects at the sensor surface, in order to increase the sensitivity and selectivity of semiconductor gas sensors for certain gas molecules [8–11]. Typical amounts of such a dopant are in the range between 0.1 and 2% w/w [12, 13].

## 2 Experimental

**2.1 Sensor fabrication** The multi-sensor chip fabricated in this work contains four identical sensing structures on a sapphire substrate with a size of  $8 \times 8 \text{ mm}^2$ . Sapphire was used as substrate due to its thermal properties. It has a lower thermal conductivity (sapphire:  $35 \text{ W mK}^{-1}$  @ 300 K) compared to common substrate materials, like silicon (Si:  $148 \text{ W mK}^{-1}$  @ 300 K), for instance. A low thermal conductivity is beneficial for a thermal insulation between the individual sensing structures on the multi-sensor chip. Furthermore, it offers high chemical stability and good thermal shock properties. Each one of the sensing structure consists of an interdigitated electrode (IDE) and a heating element. The size of the heater is approximately  $0.9 \times 0.9 \text{ mm}^2$ . A schematic of the sensor chip is shown in Fig. 1.

The sensor chips were fabricated on a 3" sapphire wafer with a thickness of  $430 \pm 20 \mu\text{m}$ . The IDE and heating elements, which consist of 200 nm platinum (Pt) and a 20 nm titanium (Ti) adhesion layer, were deposited by thermal evaporation and patterned by a lift-off process. Subsequently, a 500 nm alumina ( $\text{Al}_2\text{O}_3$ ) layer was deposited by E-beam evaporation as passivation. As a last step, the  $\text{Al}_2\text{O}_3$  layer was patterned by chemical wet etching (Micropur, BOE 7:1, 9 min) [14] in order to uncover the contact pads and IDE.

**2.2 Sensor preparation** On each one of the four structures on the chip a sensitive metal-oxide film has been deposited. As sensitive materials, n-type tin(IV)-oxide ( $\text{SnO}_2$ ) and tungsten(IV)-oxide ( $\text{WO}_3$ ), respectively, were



**Figure 1** Schematic of the multi-sensor chip on a sapphire substrate, containing four sensing structures with embedded heater (outer structure) and IDEs (inner structure).

used. While two of the structures were prepared with pure  $\text{SnO}_2$  and  $\text{WO}_3$ , the remaining two structures have been prepared with palladium- (Pd) and platinum black- (Pt) doped  $\text{SnO}_2$ , respectively. The metal oxides were available as nano-powder with a particle size smaller than 100 nm (Sigma-Aldrich, Germany). One-hundred and forty milligrams of the powders were dispersed in 1 ml distilled water [15], while the dispersions for the preparation of the Pd- and Pt-doped films contained 0.5% w/w of platinum black ( $<20 \mu\text{m}$ , Sigma-Aldrich, Germany) and palladium ( $<1 \mu\text{m}$ , Sigma-Aldrich, Germany) powder, respectively [16]. The composition of the different dispersions is summarized in Table 1.

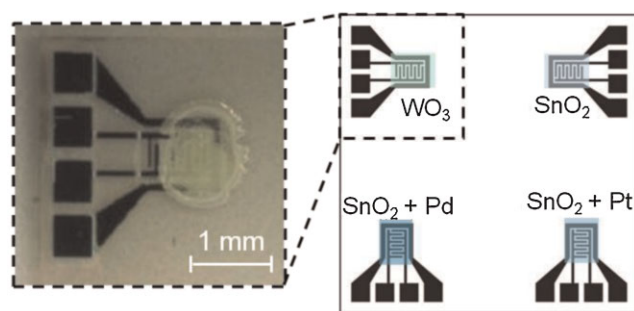
The dispersions were drop-coated onto the sensor surface with a drop volume of  $0.5 \mu\text{l}$ . Afterwards, the chip was heated up to approximately  $320^\circ\text{C}$  in order to evaporate the water and to provide adhesion of the sensing layer. A calcination of the metal-oxide films at higher temperatures than  $320^\circ\text{C}$  had to be avoided due to the fact that the thin-film resistances suffered changes in their electrical properties, as will be discussed in more detail in Section 2.3.3. Nevertheless, it was shown in previous studies, that the catalytic activity of the dopants towards  $\text{H}_2\text{O}_2$  is already activated at temperatures below  $300^\circ\text{C}$  [4]. Figure 2a provides an image of the sensor chip after the deposition of the semiconductor films. The order of the sensing films as they were deposited onto the substrate is shown in Fig. 2b.

## 2.3 Characterization

**2.3.1 XRD** Prior to the preparation of the sensor chip, the metal-oxide powders, namely  $\text{SnO}_2$  and  $\text{WO}_3$ , were

**Table 1** Composition of the dispersions used for the preparation of the sensing films.

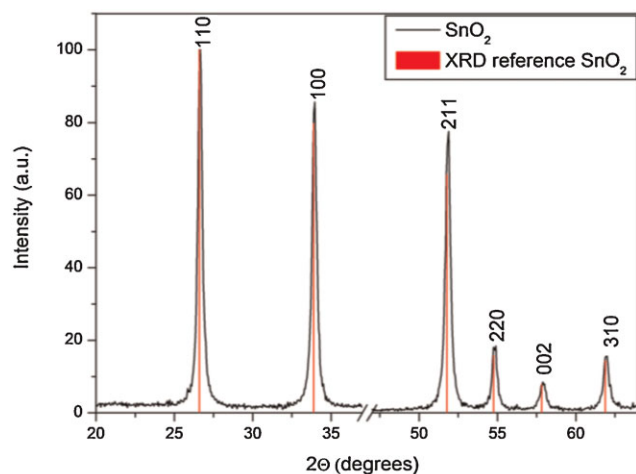
spot	metal oxide	dopant	dispensed in
1	$\text{SnO}_2$ (140 mg)	none	dest. water (1 ml)
2	$\text{SnO}_2$ (140 mg)	Pt (0.5% w/w)	dest. water (1 ml)
3	$\text{SnO}_2$ (140 mg)	Pd (0.5% w/w)	dest. water (1 ml)
4	$\text{WO}_3$ (140 mg)	none	dest. water (1 ml)



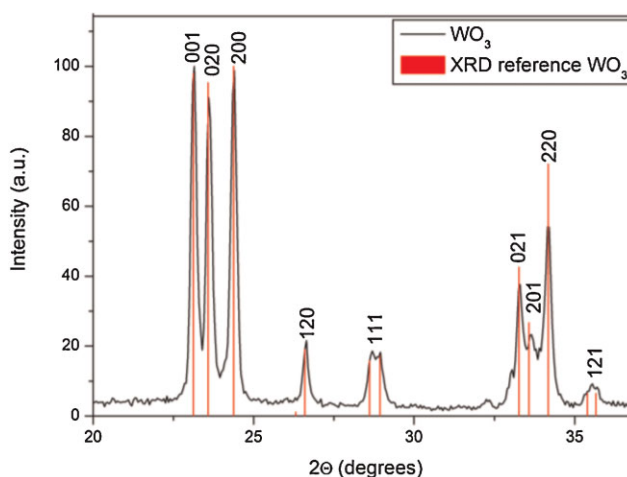
**Figure 2** (online color at: [www.pss-a.com](http://www.pss-a.com)) Microscopic image of the multi-sensor chip after the deposition of the sensing layers and schematic of the distribution of the sensing films on the chip.

investigated by X-ray diffraction analysis (XRD). Contrary to the final sensor chips, the test samples of the pure metal oxides have been prepared onto a silicon substrate as the sapphire substrates have not been available at the time of material characterization. To ensure that the results of the test samples are transferrable to the sapphire substrate, the sensitive films have been prepared in an analogous manner (see section 2.2). A Siemens D5000 diffractometer with Cu K $\alpha$  radiation ( $\lambda = 1.540598 \text{ \AA}$ ) was used to record the spectra. The XRD spectra of SnO<sub>2</sub> (Fig. 3) and WO<sub>3</sub> (Fig. 4) were monitored in a two-theta angle range from 20° to 65° and 20° to 37°, respectively.

The diffraction peaks in the XRD pattern can be indexed to the rutile phase SnO<sub>2</sub> and orthorhombic crystal structure in case of WO<sub>3</sub>, respectively, as provided by Urusov et al. [17] and Loopstra and Boldrini [18]. No characteristic peaks of impurities, such as pure metals or surfactants, were observed. The average size of the crystallites was deduced from Scherrer's formula for the strongest peaks and found to be 14 nm in case of SnO<sub>2</sub> and 27 nm in case of WO<sub>3</sub>.



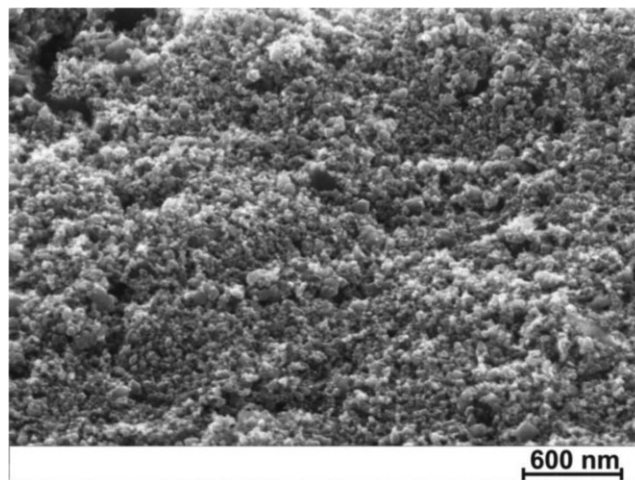
**Figure 3** (online color at: [www.pss-a.com](http://www.pss-a.com)) Indexed XRD spectrum of SnO<sub>2</sub> nano-powder prepared on a silicon substrate recorded in a two-theta angle range from 20° to 65°.



**Figure 4** (online color at: [www.pss-a.com](http://www.pss-a.com)) Indexed XRD spectrum of WO<sub>3</sub> nano-powder prepared on a silicon substrate recorded in a two-theta angle range from 20° to 37°.

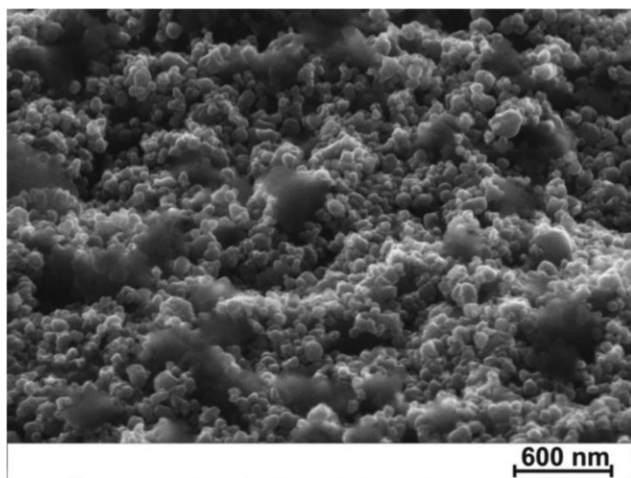
**2.3.2 SEM** In order to investigate the morphology of the sensing films, the same type of samples as used for XRD have been analyzed by scanning electron microscopy (SEM), as the sapphire substrates had not been available at the time of material characterization. Still, the properties of the sensing films should be comparable to those on sapphire substrate as the method of preparation was exactly the same. Figures 5 and 6 show the SEM images of the prepared samples with SnO<sub>2</sub> (Fig. 5) and WO<sub>3</sub> (Fig. 6) with a magnification of approximately 100 k.

Both, the SnO<sub>2</sub> and WO<sub>3</sub> samples depict a rough and highly covered surface, which is favorable in terms of gas sensing, especially in the lower concentration range. The average size of the crystallites observed in SEM images is consistent with the results obtained from the XRD patterns.



**Figure 5** SEM image of an SnO<sub>2</sub> film prepared on a silicon substrate at a magnification of approximately 100 k.





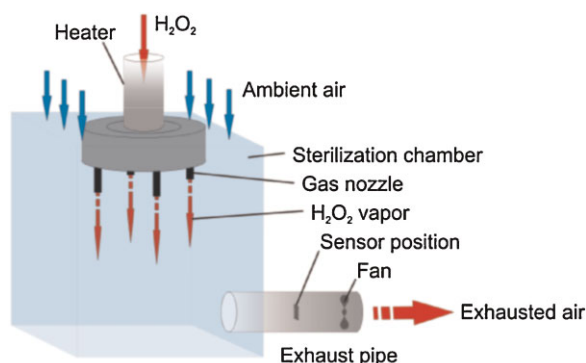
**Figure 6** SEM image of a  $\text{WO}_3$  film prepared on a silicon substrate at a magnification of approximately 100 k.

**2.3.3 Thermal characterization** In order to determine the resistance ( $R_0$ ) and thermal coefficient ( $\alpha$ ) of the heating elements, a comparison calibration in a defined temperature bath has been done in several steps between 20 and 80 °C. From the average of four sensor chips (16 heaters) out of one charge,  $R_0$  was found to be  $17.41 \pm 0.64 \, \Omega$  and  $\alpha = 3.12 \times 10^{-3} \pm 3.4 \times 10^{-5} \, \text{K}^{-1}$ . The determined value for  $\alpha$  is in good accordance with the values obtained for Ti/Pt thin-film resistances by Groenland [19].

The sensor chip was designed in a way that each sensing structure can be heated individually. Nevertheless, for the sensor characterization the four heaters were operated with a single voltage source in parallel. In order to achieve an operating temperature of  $320 \pm 2 \, ^\circ\text{C}$  in the gas stream (air flow of  $70 \, \text{m}^3 \text{h}^{-1}$ , gas temperature of  $70 \, ^\circ\text{C}$ ), a voltage of 6 V was applied to the heaters, resulting in a current of 688 mA and an overall power consumption of 4.1 W.

In a further experiment, it was found that an excessive heating of the sensor chips caused changes in the electric properties of the heating elements. At chip temperatures  $>400 \, ^\circ\text{C}$ , the platinum–titanium bilayer thin-film resistances were subject to interlayer diffusion and stress-induced morphological changes, as it was confirmed by the investigations of Groenland [19]. This led to an  $>100\%$  increase of the nominal resistance  $R_0$  as well as to changes in the thermal coefficient  $\alpha$ . In order to avoid changes in the thermal properties of the sensor chip during the film deposition and later on during the measurements, its maximum operating temperature had to be reduced to  $320 \, ^\circ\text{C}$ .

**2.4 Experimental set-up** For the characterization of the sensing properties, the sensor chip was attached to a printed circuit board (PCB) and contacted via bond wires. The sensor chip was located in the exhaust pipe of an aseptic sterilization chamber, which is continuously flooded



**Figure 7** (online color at: [www.pss-a.com](http://www.pss-a.com)) Schematic of the experimental set-up for the generation of hydrogen-peroxide vapor.

with hydrogen peroxide vapor. Therefore, a technical grade aqueous hydrogen peroxide solution of 35% w/w is fed to a flow-controlled air stream, which is supplied by compressed air. Subsequently, the gas–liquid-mixture is evaporated in a heater. For a detailed description of the  $\text{H}_2\text{O}_2$ -vapor generation unit is referred to Ref. [4]. While hydrogen peroxide is vaporized into the chamber at an air flow of  $10 \, \text{m}^3 \text{h}^{-1}$ , the exhauster provides a continuously discharge of  $70 \, \text{m}^3 \text{h}^{-1}$ . The  $60 \, \text{m}^3 \text{h}^{-1}$  lack between the  $\text{H}_2\text{O}_2$  vapor entry ( $10 \, \text{m}^3 \text{h}^{-1}$ ) and the suction capacity of the exhauster ( $70 \, \text{m}^3 \text{h}^{-1}$ ) is being compensated by aspiration of ambient air via venting slots. As a result, the  $\text{H}_2\text{O}_2$  concentration in the exhausted air is being diluted to 1/7 of its initial concentration in gaseous phase. Since, according to the knowledge of the authors, no reference method for the detection of hydrogen peroxide under the given conditions (broad concentration range and high flow) has been available, it was assumed that the dosed amount of hydrogen peroxide fully passes over into the gaseous phase and will be present at the point of measurement. The discharge of  $70 \, \text{m}^3 \text{h}^{-1}$  was checked with a flow meter. The diameter of the exhaust pipe is 10 cm. A schematic of the experimental set-up is shown in Fig. 7.

### 3 Results and discussion

**3.1 Measurements** For the characterization of the sensor response to hydrogen peroxide, various concentrations of  $\text{H}_2\text{O}_2$  in the exhaust air stream, ranging from 5 to 1000 ppm, have been provided. The concentration steps in between were 10, 50, 100, and 500 ppm, respectively. After the vaporization system was heated up to a stable operating temperature, the vaporization by  $\text{H}_2\text{O}_2$  was started. Initially, a concentration of 5 ppm  $\text{H}_2\text{O}_2$  was provided for 10 min, following a stepwise increase of the  $\text{H}_2\text{O}_2$  concentration up to the maximum concentration of 1000 ppm and in return a stepwise decrease down to 5 ppm. Each concentration step was kept for 10 min. The hydrogen peroxide has been vaporized to the sterilization chamber at a temperature of  $270 \, ^\circ\text{C}$ . By dilution with ambient air, the gas stream reaches a temperature of about  $70 \, ^\circ\text{C}$  in the exhaust pipe.

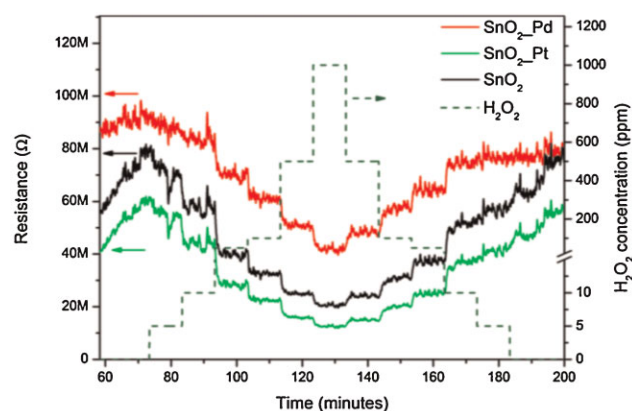
**3.2 H<sub>2</sub>O<sub>2</sub> sensing** The sensor chip with four different types of metal-oxide films was investigated for H<sub>2</sub>O<sub>2</sub> concentrations between 5 and 1000 ppm. Figure 8 presents the recorded measurement data for the SnO<sub>2</sub> as well as Pd- and Pt-doped SnO<sub>2</sub> films in one diagram.

Prior to the exposure of H<sub>2</sub>O<sub>2</sub>, the system has to reach steady conditions in terms of flow and temperature in the exhaust pipe ( $t < 70$  min). In this way, it was also ensured that the operating temperature of the sensor chip is not being influenced by alterations of the temperature in the exhaust air. This condition was assumed to be fulfilled when the relative change in resistance of the sensing films was less than 1% of the absolute resistance value per minute ( $t = 70$  min). At this point, the resistances are in the same order of magnitude between approximately 60 and 90 MΩ. To the exposure of H<sub>2</sub>O<sub>2</sub>, the sensors respond with a decrease in their resistance and with further increase of the H<sub>2</sub>O<sub>2</sub> concentration, the resistances of the different sensors decrease gradually. After the exposure to the highest concentration of 1000 ppm H<sub>2</sub>O<sub>2</sub>, the resistance values raise again towards lower concentrations. After the exposure to H<sub>2</sub>O<sub>2</sub> was stopped at  $t = 182$  min, the resistances of the SnO<sub>2</sub> and Pt-doped SnO<sub>2</sub> films raise to similar values as prior to the exposure of H<sub>2</sub>O<sub>2</sub> ( $t = 70$  min). In case of the Pd-doped sensor, the resistance of the sensing film is somewhat lower compared to its initial value.

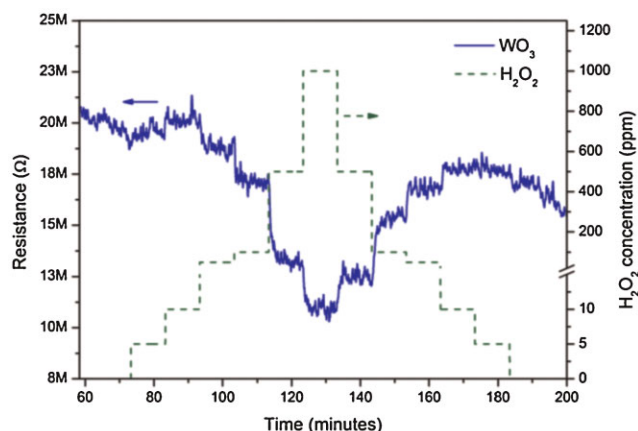
The resistance behavior of the WO<sub>3</sub> sensor was recorded in parallel and is shown in Fig. 9.

The initial resistance value of the WO<sub>3</sub> film is around 20 MΩ, thus slightly lower compared to the SnO<sub>2</sub> and doped SnO<sub>2</sub> films. The response of the WO<sub>3</sub> sensor is similar compared to the other sensors, however, it is subject to a higher drift.

In order to characterize the sensor behavior and to compare the different materials, the relative resistance values of all sensors were plotted in a single diagram. Therefore, the resistance values ( $R$ ) of the individual sensors at each concentration step were divided by the initial resistance value ( $R_0$ ) before the exposure to H<sub>2</sub>O<sub>2</sub>



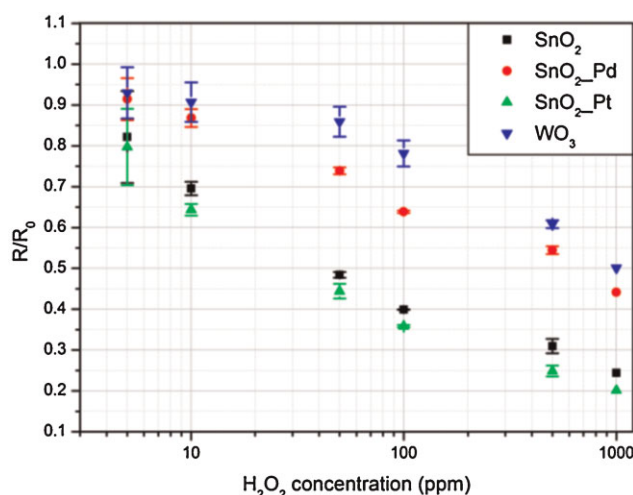
**Figure 8** (online color at: [www.pss-a.com](http://www.pss-a.com)) Measurement data of the undoped, Pt-, and Pd-doped SnO<sub>2</sub> gas sensors in hydrogen peroxide atmosphere.



**Figure 9** (online color at: [www.pss-a.com](http://www.pss-a.com)) Measurement data of the WO<sub>3</sub> gas sensor in hydrogen peroxide atmosphere.

( $t = 70$  min). Figure 10 overviews the calibration plots of the four sensors for a logarithmic scale of the H<sub>2</sub>O<sub>2</sub> concentration. The plotted values correspond to the mean values of the sensor signals for equal concentrations, recorded once towards higher concentrations and towards lower concentrations, respectively. The error bars represent the standard deviation of these values.

All types of sensors exhibit a linear correlation between the change in their relative resistance and the logarithm of the H<sub>2</sub>O<sub>2</sub> concentration in the range between 5 and 1000 ppm. The lowest sensitivity was observed for the WO<sub>3</sub> film, followed by the Pd-doped SnO<sub>2</sub> sensor. Also, the reproducibility of the WO<sub>3</sub> sensor is lower compared to the other ones (compare error bars in Fig. 10). The Pt-doped SnO<sub>2</sub> offered the highest sensitivity to H<sub>2</sub>O<sub>2</sub> in the ppm range, whereas it was slightly lower in case of undoped SnO<sub>2</sub>. The LOD for hydrogen peroxide was found to be 5 ppm in

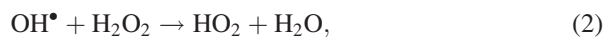


**Figure 10** (online color at: [www.pss-a.com](http://www.pss-a.com)) Calibration plot of a SnO<sub>2</sub>, WO<sub>3</sub>, Pt-, and Pd-doped SnO<sub>2</sub> gas sensor for H<sub>2</sub>O<sub>2</sub> concentrations in the ppm range.

case of the undoped and Pt-doped  $\text{SnO}_2$ , 10 ppm for Pd-doped  $\text{SnO}_2$  and 50 ppm in case of the  $\text{WO}_3$  film.

Considering the relative resistance changes of the sensitive layers, it is found that, for example, in case of the undoped  $\text{SnO}_2$  sensor, the relative change of the resistance ( $R/R_0$ ) upon exposure of hydrogen peroxide is about 1/2.5 per decade. This seems somewhat low compared to the sensitivities that are typically achieved with n-type semiconductor gas sensors when exposed to oxidizing or reducing gases. These are typically in the range of 3/1 for oxidizing gases such as  $\text{O}_2$  up to a ratio of 5/1 for reducing gases such as  $\text{H}_2$  or methane, for instance [20]. In earlier works however, similar sensitivities as by the results presented here have been observed upon the exposure of commercially available n-type semiconductor gas sensors with  $\text{H}_2\text{O}_2$  in the lower percent range [7].

The fact that the resistivity of the sensors decreases under exposure to  $\text{H}_2\text{O}_2$  seems not to be in accordance with the expected behavior of n-type metal-oxide-semiconductor materials, which exclusively were used in this case, when in contact to oxidizing gases, like hydrogen peroxide. It is generally considered that, in case of n-type metal-oxide-semiconductor gas sensors, reducing gases react with adsorbed oxygen ions at the metal-oxide surface, so releasing bound electrons, which are then free to conduct. As a result, the resistance of the surface layer decreases. For an oxidizing gas, the converse mechanism will operate and the resistance will rise [21]. Though, the same type of behavior was observed in previous studies for the exposure to  $\text{H}_2\text{O}_2$  in a higher concentration range using commercially available n-type semiconductor gas sensors with not exactly specified composition of the sensing films [7]. To explain the decrease of the resistance with increasing  $\text{H}_2\text{O}_2$  concentration, one has additionally to take into consideration the mechanism of reaction concerning the decomposition of  $\text{H}_2\text{O}_2$ . Although the complete mechanism is not completely uncovered yet,  $\text{H}_2\text{O}_2$  is known to decompose to  $\text{H}_2\text{O}$  and  $\text{O}_2$  following a pathway provided by Hiroki and LaVerne [22]:



The occurrence of hydroxyl radicals ( $\text{OH}^\bullet$ ) according to Eq. (2), knowing they are of transitory nature, was proven to have a strong influence on the electrical conductivity of n-type metal oxides as they react with adsorbed oxygen molecules at the metal-oxide surface leading to a decrease in the resistance [23]. As Pd and Pt are known to have a high catalytic activity towards  $\text{H}_2\text{O}_2$  [15] it was presumed that doping by these two materials may increase the sensitivity due to an enhanced reaction of  $\text{H}_2\text{O}_2$  at the metal-oxide surface. In case of the Pt-doped  $\text{SnO}_2$  a slightly higher sensitivity compared to the undoped  $\text{SnO}_2$  was observed, which might be the result of a catalytical reaction of  $\text{H}_2\text{O}_2$

at the Pt particles. In case of the Pd-doped  $\text{SnO}_2$ , which exhibits a lower sensitivity to  $\text{H}_2\text{O}_2$  compared to undoped  $\text{SnO}_2$ , the sensing mechanism seems to be more complex. One proposal could be that the Pd particles catalytically activate the dissociation of molecular oxygen. As a result, its atomic products then diffuse to the metal oxide increasing both, the quantity of oxygen that will rebind vacancies on the  $\text{SnO}_2$  surface as well as the rate at which rebinding occurs, resulting in a greater degree of electron withdrawal from the  $\text{SnO}_2$ . This mechanism is well established in the catalysis literature and dates back to the 1960s. In this context, Boudart et al. [24] coined the term “spillover effect”.

The impact of humidity on the sensor response has not been studied in detail. Generally, n-type semiconductors as the presented  $\text{SnO}_2$  and  $\text{WO}_3$  gas sensors are known to be humidity-sensitive. As for the sensor calibration a 35% w/w aqueous hydrogen peroxide solution was used, the  $\text{H}_2\text{O}_2$  concentrations in gaseous phase have been regulated by adjusting the dosed amount of the aqueous solution. It is therefore generally assumed that  $\text{H}_2\text{O}_2$  and  $\text{H}_2\text{O}$  will be present in the same mass ratio, regardless of the absolute dosage. In this way, similar conditions arise upon the exposure to different concentrations of hydrogen peroxide. Measurements with commercially available sensors of the same type under  $\text{H}_2\text{O}_2$  atmosphere have shown that  $\text{H}_2\text{O}$  shifted the sensor signal of an n-type semiconductor in the same direction such as hydrogen peroxide. However, the response on  $\text{H}_2\text{O}_2$  was about ten times higher [7].

**4 Conclusions** A multi-sensor chip with four individually controllable sensing structures was fabricated and deposited with different types of metal oxides. Both, the  $\text{SnO}_2$  and  $\text{WO}_3$  layers seem to be promising candidates for hydrogen peroxide sensing in the ppm concentration range. Regarding the sensing mechanism of the doped  $\text{SnO}_2$  films, still some questions remain unanswered. However, it could be shown that doping of  $\text{SnO}_2$  by platinum black increases the sensitivity towards  $\text{H}_2\text{O}_2$ . The lower detection limit was found to be 5 ppm. In this study,  $\text{SnO}_2$  films showed a higher reproducibility compared to  $\text{WO}_3$  films.

Even though that the sensor response on  $\text{H}_2\text{O}_2$  is less pronounced as compared to typical target gases such as hydrocarbons, its usability in the illustrated application seems justified, as there are currently no suitable reference methods for the detection of hydrogen peroxide in exhaust systems that cover such wide measuring range, which potentially spans from the low ppm range up to the percent range. A statement on the lifetime of the multi-sensor, especially in continuous use under exposure to  $\text{H}_2\text{O}_2$ , cannot be taken at this time. However, a lifetime of several months would be desirable and seems to be reasonable. Another challenge is yet to detect  $\text{H}_2\text{O}_2$  concentrations below 5 ppm, to make the sensor feasible for workplace monitoring in terms of TLV.

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